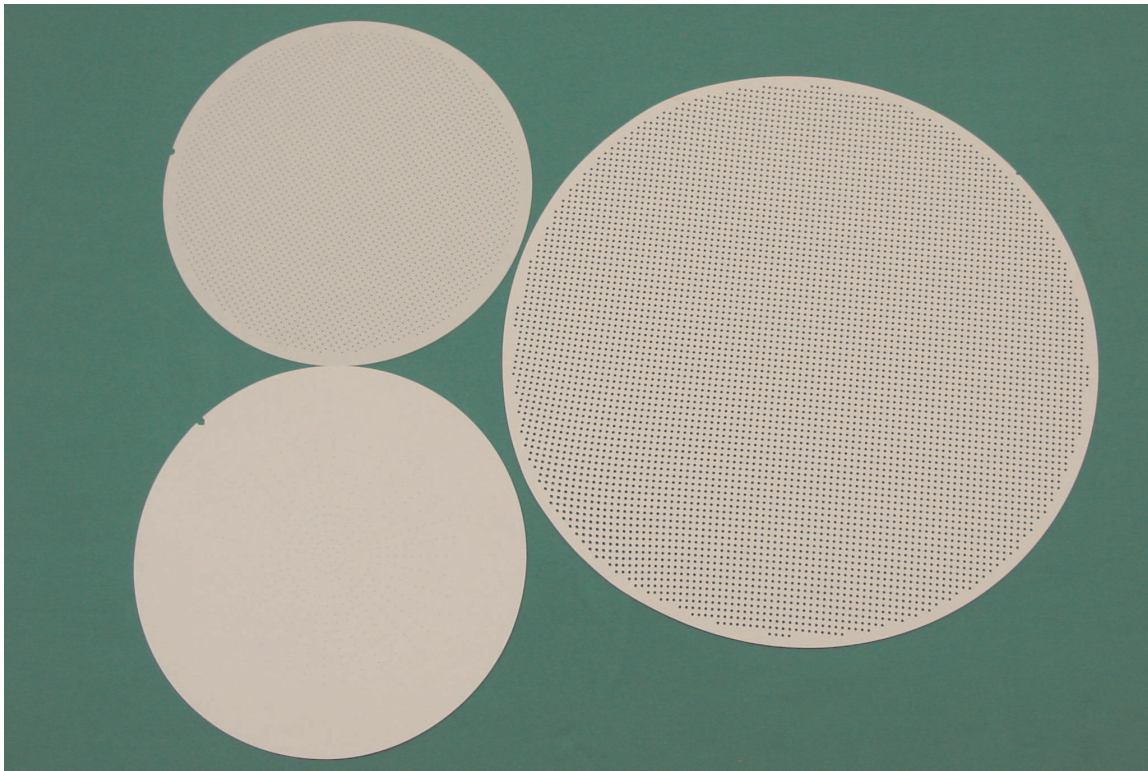


THIN WAFER & FILM CARRIERS



ULTRA FLAT RIGID CERAMIC CARRIERS FOR FLEXIBLE SUBSTRATE

FEATURES

- Ultra flat
- Large sizes
- Vacuum clamping
- Sub-surface marking
- Physical stops
- Selectable thickness

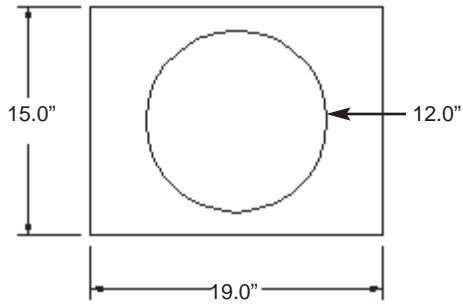
Our carriers are used to hold and transport thinned silicon wafers and flexible substrates. These products can be supplied ready for substrate attachment with or without holes or registration aids. Vacuum can be transferred via holes as small as .004 inch or by the use of porous ceramic which provides continuous substrate support. Wafer carriers can be supplied with customized orientation legending as well as with physical mechanical stops. All thin substrate carriers are ultra flat and are fabricated to a standard flatness spec of .0002 inches/inch. Carriers are fabricated to the customer's requirements and quoted per request. Current sizes can be as large as 15.0 x 19.0 inches (381 x 482 mm). Any shape within our maximum size is possible.



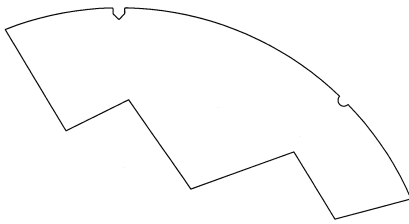
CERAMIC SUPPLY INTERNATIONAL, INC.

1230 COLEMAN AVE., SANTA CLARA, CA 95050

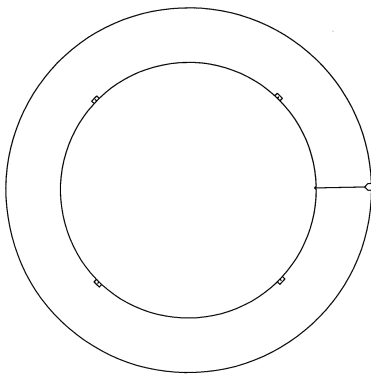
TEL; 408-727-0100 FAX: 408-727-2100 EMAIL: gen@fjaind.com.



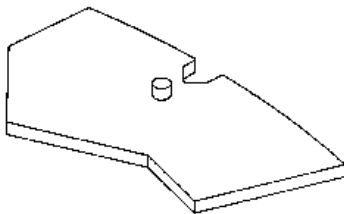
Diameters of any size to 381mm (15.00 inch)
Part sizes above 381 mm require special tooling charges.



Orientation features are customer specified and almost any shape is available. Both leg-
ending and physical mechanical stops are available.



Surface legending is customer defined and unlimited. All markings are permanent and will not degrade with cleaning or use provid-
ing temperatures do not exceed 700°C. All marking is sub-surface and will not impact flatness.



Physical stops and positioning aids are avail-
able to rapidly orient products to carriers.
These aids are customer defined and numer-
ous in design.